

**Product Summary**

$V_{CE}$	650 V
$I_C$	50A @ $T_c=100^{\circ}\text{C}$
$V_{CE(sat),Typ}$	1.55V @ $I_c=50\text{A}$

**Trench Field Stop IGBT Co-packed with SiC Schottky Barrier Diode**

**Features**

- Low  $V_{CE(sat)}$
- Trench FS Technology
- High Speed Switching
- Hybrid SiC Discrete Devices
- Halogen Free, RoHS Compliant

**Applications**

- UPS
- PV Inverter
- Welding Machine
- On-board Charger
- Totem Pole Bridgeless PFC
- High Frequency Motor Drive

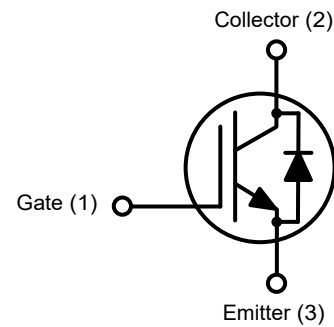
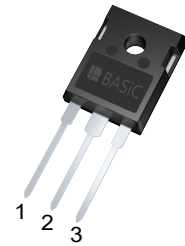
**Package Pin Definitions**

- Pin1 - Gate
- Pin2 - Collector & Backside
- Pin3 - Emitter

**Package Parameters**

Part Number	Marking	Package
BGH50N65HF1	BGH50N65HF1	TO-247-3

**Package: TO-247-3**



**Maximum Ratings ( $T_c=25^\circ\text{C}$  Unless Otherwise Noted)**

Symbol	Parameter		Value	Unit
$V_{CE}$	Collector-Emitter Voltage, $T_j \geq 25^\circ\text{C}$		650	V
$V_{GE}$	Gate-Emitter Voltage		$\pm 20$	
	Transient Gate-Emitter Voltage		$\pm 30$	
$I_C$	DC Collector Current, limited by $T_{jmax}$	$T_c=25^\circ\text{C}$	114	A
		$T_c=100^\circ\text{C}$	50	
$I_F$	Diode Forward Current, limited by $T_{jmax}$	$T_c=25^\circ\text{C}$	50	A
		$T_c=100^\circ\text{C}$	34	
$I_{C,pulse}$	Pulse Collector Current	$V_{GE}=15\text{V}$ , $t_p$ limited by $T_{jmax}$	200	A
$P_{tot}$	Power Dissipation	$T_c=25^\circ\text{C}$	297	W
$T_j$	Operating Junction Temperature		-40~150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range		-55~150	$^\circ\text{C}$
$M_d$	TO-247 mounting torque	M3 Screw	0.7	Nm

**Thermal Resistance**

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(j-c)}$	IGBT Thermal Resistance-Junction to Case		0.42		K/W
$R_{th(j-c)}$	Diode Thermal Resistance-Junction to Case		0.81		K/W
$R_{th(j-a)}$	Thermal Resistance-Junction to Ambient		32		K/W

**Electrical Characteristics (Defined at  $T_j=25^\circ\text{C}$  Unless Otherwise Specified)**
**IGBT Static Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15\text{V}$ , $I_C=50\text{A}$	$T_j=25^\circ\text{C}$		1.55	2.1	V
			$T_j=100^\circ\text{C}$		1.75		
			$T_j=150^\circ\text{C}$		1.88		
$I_{CES}$	Zero Gate Voltage Drain Current	$V_{CE}=650\text{V}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$			100	$\mu\text{A}$
			$T_j=150^\circ\text{C}$			1000	
		$V_{CE}=480\text{V}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$			80	
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$	$T_j=25^\circ\text{C}$			100	nA

$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=500\mu A$	$T_J=25\text{ }^\circ\text{C}$	4.2	5	5.8	V
$g_{fs}$	Transconductance	$V_{CE}=20V, I_C=40A$			82		S

### Dynamic Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$C_{ies}$	Input Capacitance	$V_{GE}=0V, V_{CE}=25V$ $f=250kHz$		5692		pF
$C_{oes}$	Output Capacitance			339		pF
$C_{res}$	Reverse Transfer Capacitance			95		pF
$Q_G$	Internal Gate Resistance	$V_{CC}=520V, V_{GE}=15V, I_C=50A$		308		nC

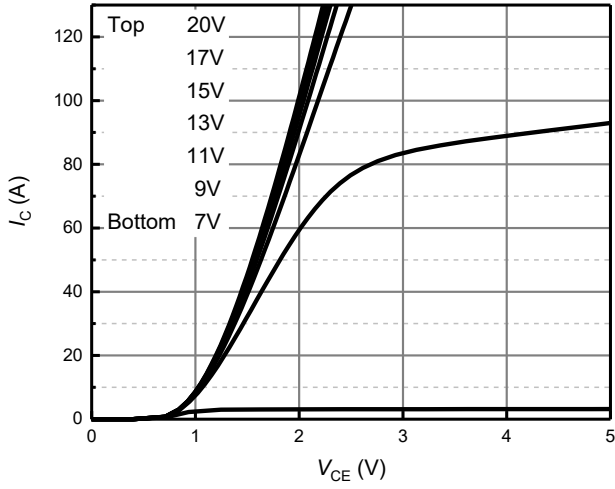
### Switching Characteristics, Inductive Load

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-On Delay Time	$T_J=25\text{ }^\circ\text{C}$ $V_{DC}=400V, I_C=25A$ $V_{GE}=0/15V, R_{G(ext)}=10\Omega$ $L_\sigma=60nH$		23		ns
$t_r$	Rise Time			27		
$t_{d(off)}$	Turn-Off Delay Time			333		
$t_f$	Fall Time			42		
$E_{on}$	Turn-On Energy			357		uJ
$E_{off}$	Turn-Off Energy			343		
$E_{total}$	Total Switching Energy			700		

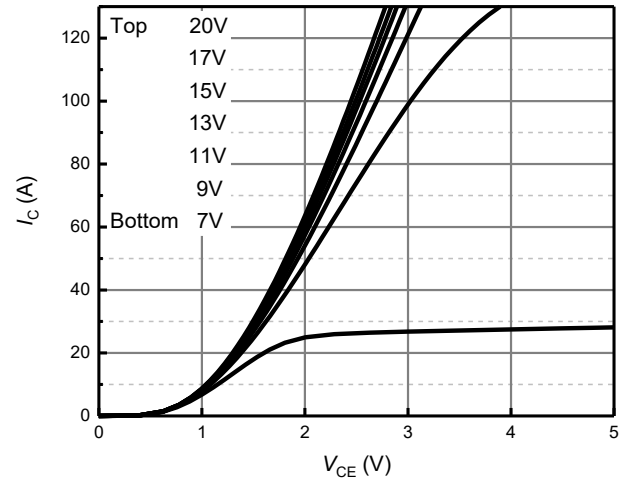
### SiC Schottky Barrier Diode Static Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$V_F$	Diode Forward Voltage	$I_F=20A, V_{GE}=0V$	$T_J=25\text{ }^\circ\text{C}$	1.51		V
			$T_J=100\text{ }^\circ\text{C}$	1.62		
			$T_J=150\text{ }^\circ\text{C}$	1.76		
$Q_C$	Diode Capacitive Charge	$V_R=400V, T_J=25\text{ }^\circ\text{C}$		46		nC
C	Diode Capacitance	$V_R=1V, f=1MHz$		713		pF
		$V_R=300V, f=1MHz$		79		

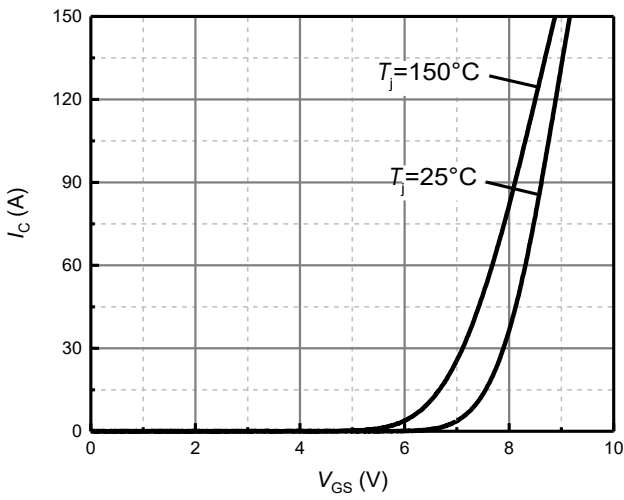
**Typical Performance**



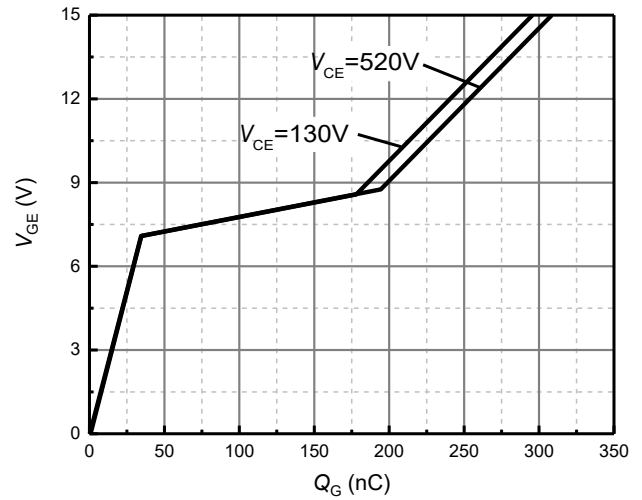
**Figure 1 Output Characteristics**  
( $T_j=25^\circ\text{C}$ )



**Figure 2 Output Characteristics**  
( $T_j=150^\circ\text{C}$ )

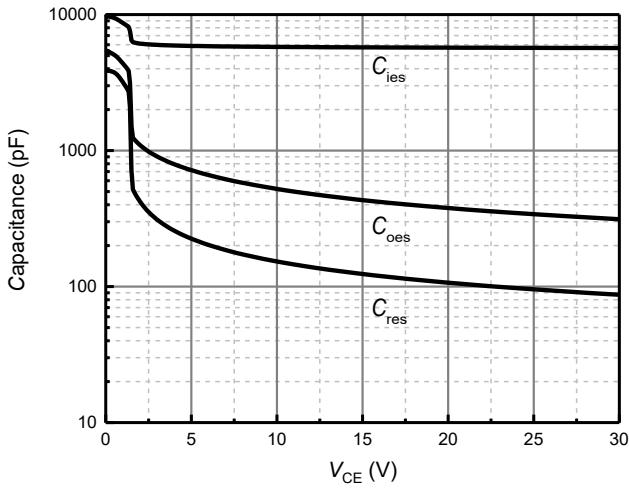


**Figure 3 Transfer Characteristics for Various Temperature**  
( $V_{CE}=20\text{V}$ )

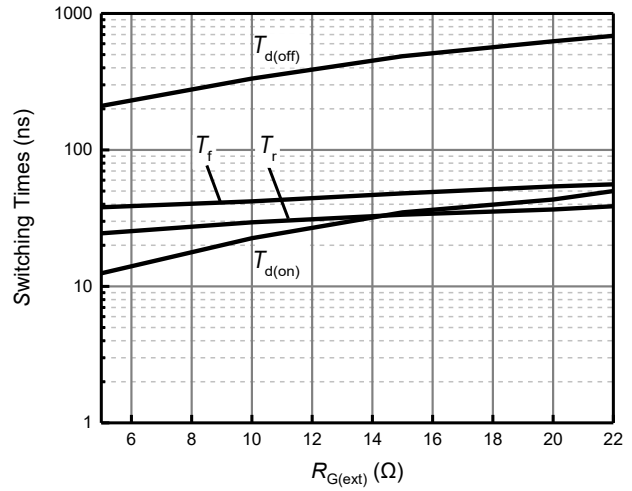


**Figure 4 Gate Charge Characteristics**  
( $I_C=50\text{A}$ )

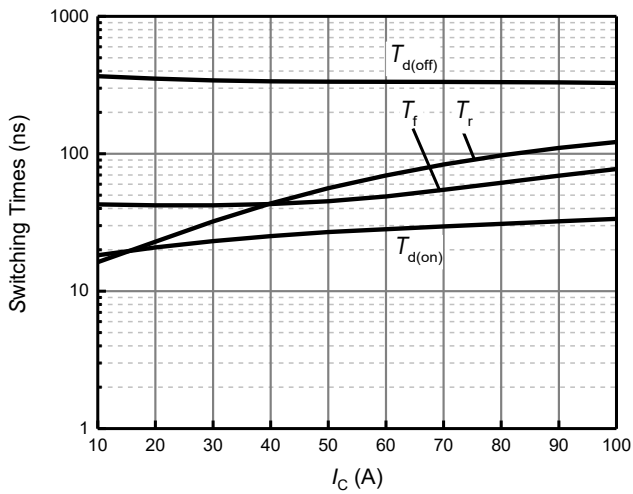
**Typical Performance**



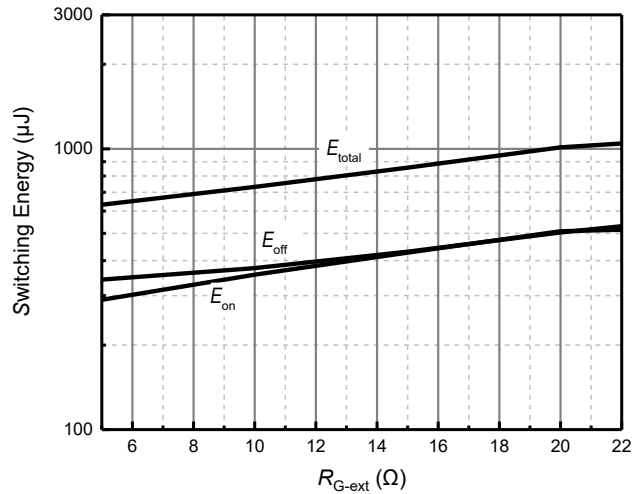
**Figure 5** Capacitance Characteristics  
( $V_{GE}=0V$ ,  $f=250kHz$ )



**Figure 6** Switching Times vs. Gate Resistor  
( $V_{DC}=400V$ ,  $V_{GE}=0/15V$ ,  $I_C=25A$ ,  $T_j=25^\circ C$ )

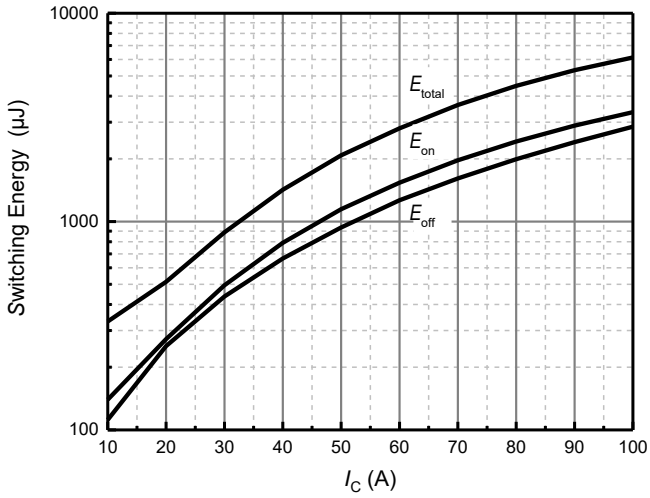


**Figure 7** Switching Times vs. Collector Current  
( $V_{DC}=400V$ ,  $V_{GE}=0/15V$ ,  $R_{G(ext)}=10\Omega$ ,  $T_j=25^\circ C$ )

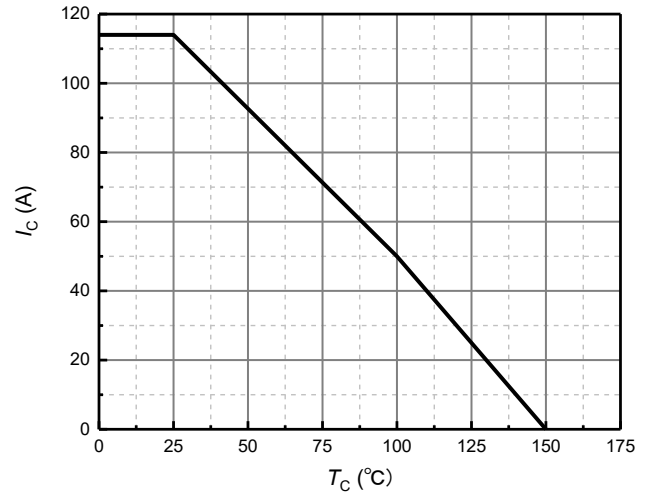


**Figure 8** Switching Loss vs. Gate Resistor  
( $V_{DC}=400V$ ,  $V_{GE}=0/15V$ ,  $I_C=25A$ ,  $T_j=25^\circ C$ )

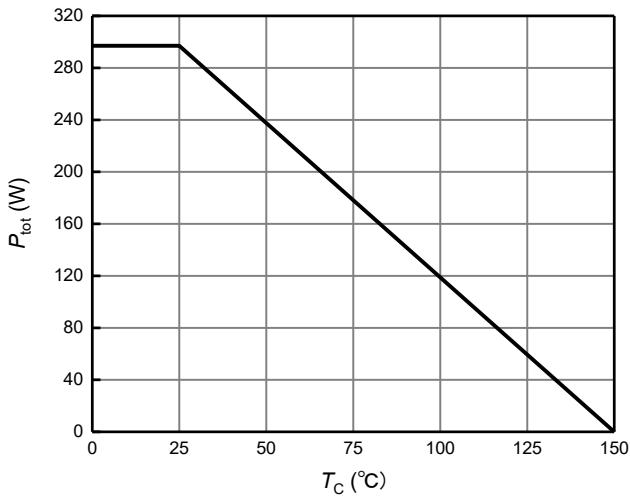
**Typical Performance**



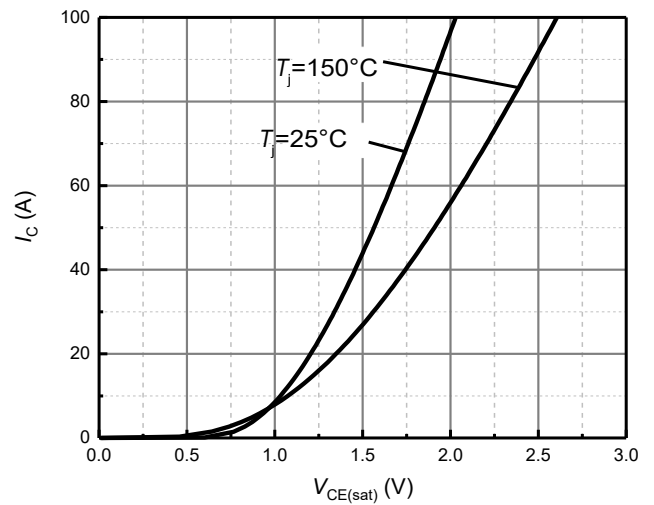
**Figure 9 Switching Loss vs. Collector current** ( $V_{DC}=400V$ ,  $V_{GE}=0/15V$ ,  $R_{G(ext)}=10\Omega$ ,  $T_j=25^\circ C$ )



**Figure 10 Collector current vs. Case Temperature**

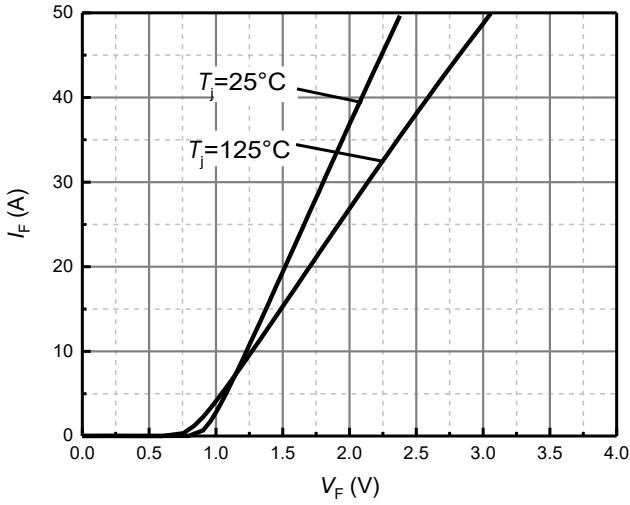


**Figure 11 Power Dissipation vs. Case Temperature**

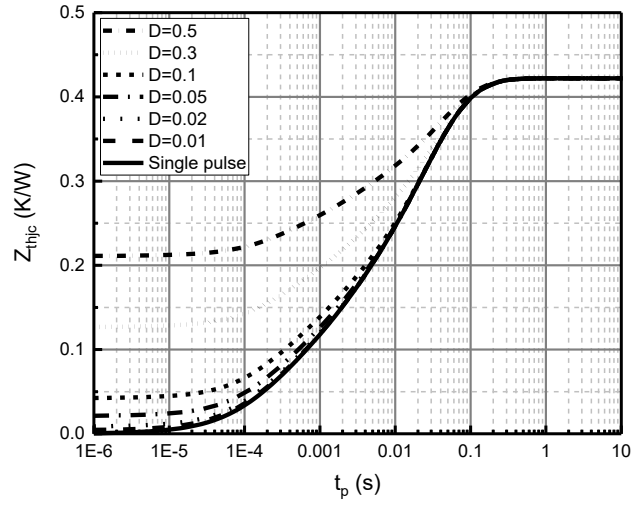


**Figure 12 Collector-emitter saturation voltage for Various Temperature** ( $V_{GE}=15V$ )

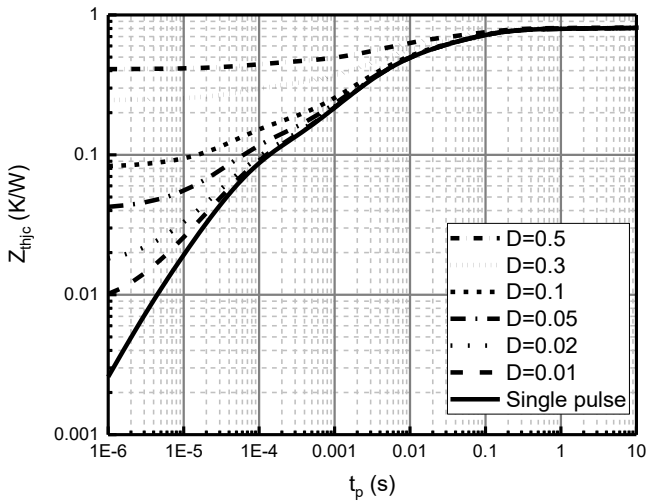
**Typical Performance**



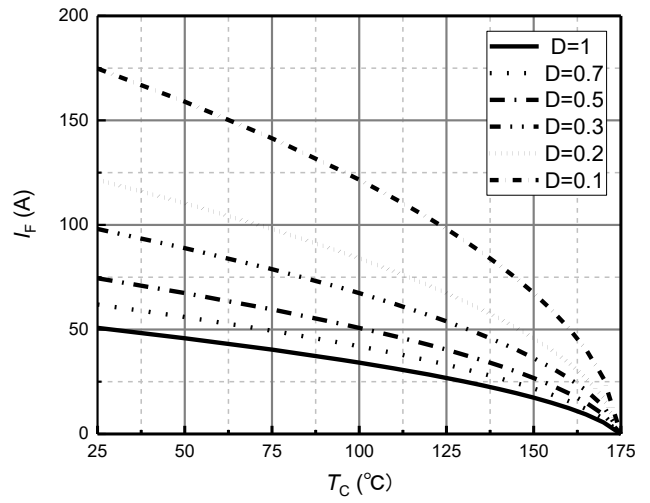
**Figure 13 Forward characteristic of Diode**



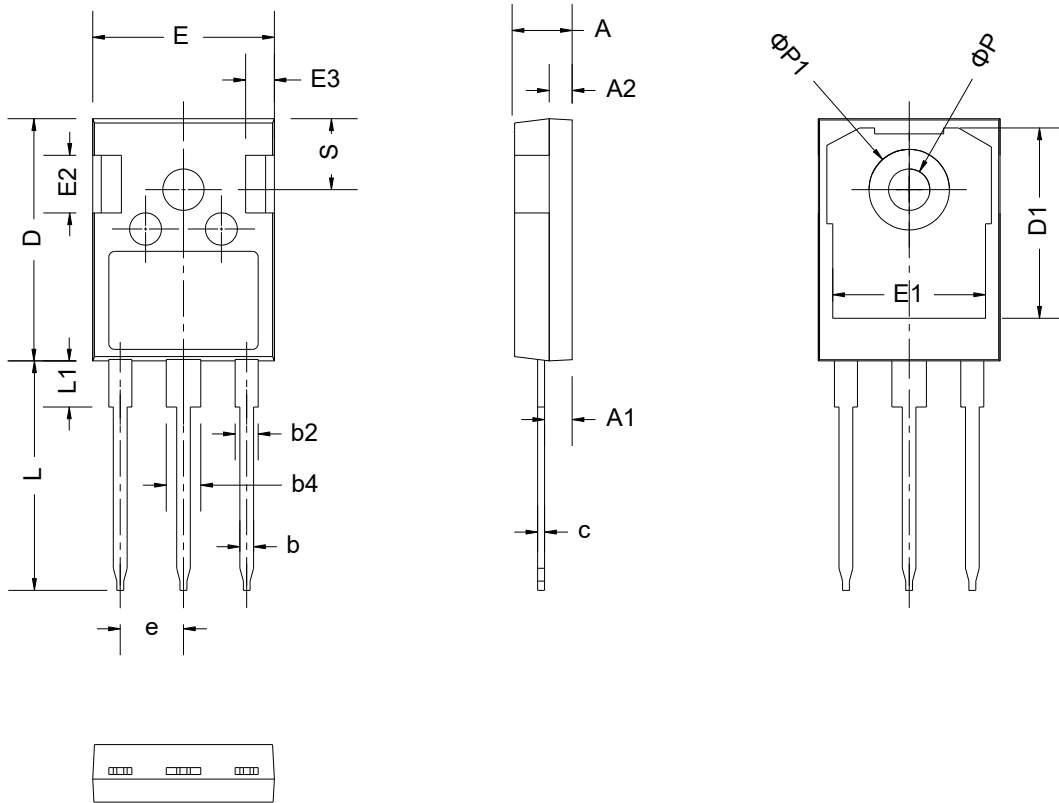
**Figure 14 IGBT Transient Thermal Response Curve**



**Figure 15 Diode Transient Thermal Response Curve**



**Figure 16 Diode forward current as function of temperature, D=duty cycle**

**Package Dimensions**


Items	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.8	5.00	5.20
E3	2.3	2.50	2.70
e	5.44 BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
φ P	3.40	3.60	3.80
φ P1	-	-	7.30
S	6.16 BSC		



**Revision History**

<b>Document Version</b>	<b>Date of Release</b>	<b>Description of Changes</b>
Rev 0.0	2022-05-16	Draft datasheet created.

**BASiC Semiconductor Ltd.**  
**Shenzhen, China**  
**© 2022 BASiC Semiconductor Ltd.**  
**All Rights Reserved.**

**Information**

For further information on technology, delivery terms and conditions and prices, please contact the nearest BASiC Semiconductor Office

**Disclaimer**

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, BASiC semiconductor Ltd. hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [IGBT Transistors](#) category:*

*Click to view products by [BASiC Semiconductor](#) manufacturer:*

Other Similar products are found below :

[IRG4PC30W](#) [APT20GT60BRDQ1G](#) [STGWA25H120DF2](#) [APT30GS60BRDQ2G](#) [TIG058E8-TL-H](#) [IDW40E65D2](#) [IXGF30N400](#)  
[STGB40V60F](#) [STGWA25H120F2](#) [NGTB75N65FL2WAG](#) [2MBI150VA-060-50](#) [NTE3320](#) [FGD3040G2-F085](#) [FGD3440G2-F085](#)  
[STGW80H65DFB-4](#) [AFGY160T65SPD-B4](#) [IGW30N60TP](#) [IGW40N60TP](#) [IGW50N60TP](#) [IHW30N65R5](#) [IKFW40N60DH3E](#) [IKP15N65H5](#)  
[IKQ100N60T](#) [IKQ120N60T](#) [IKW30N65WR5](#) [IKW75N60H3](#) [IKZ50N65NH5](#) [IKZ75N65NH5](#) [FGD3040G2-F085C](#) [FGH4L50T65SQD](#)  
[FGHL40T65MQDT](#) [FGHL50T65MQD](#) [FGHL50T65MQDTL4](#) [FGHL75T65LQDT](#) [FGHL75T65MQD](#) [FGHL75T65MQDT](#)  
[FGHL75T65MQDTL4](#) [FGY75T120SWD](#) [EL3120S1\(TA\)\(SAS\)-V](#) [IHW15N120E1](#) [IKQ75N120CS6](#) [IKA08N65ET6](#) [IKW50N65WR5](#)  
[MG150HF12MIC2](#) [SL15T65FK](#) [KGF50N65KDF-U/H](#) [IHW40N65R5S](#) [IKQ75N120CH3](#) [IHW30N160R5](#) [SGM100HF12A1TFD](#)